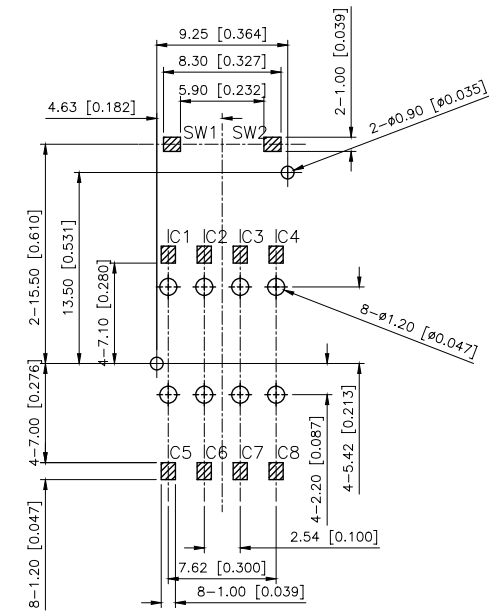
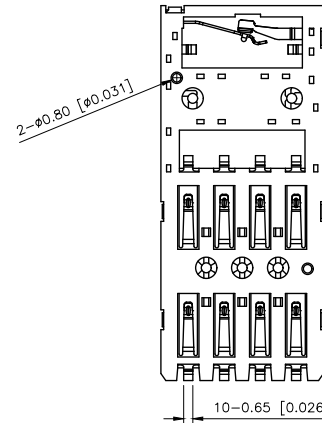
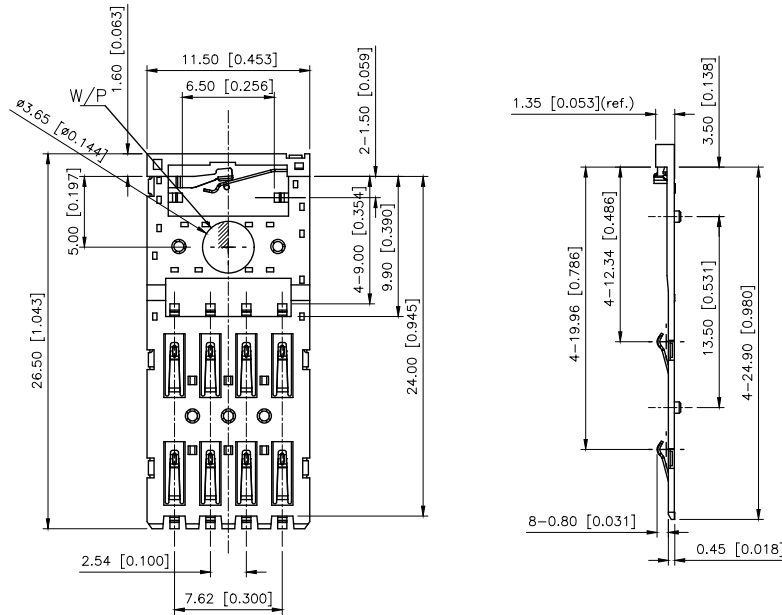
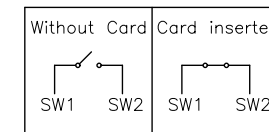


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树



BOARD PAD HOLE

Recommended PCB Layout
General Tolerance: ±0.05mm



NOTE:

- 材料 Material:
1-1 胶壳 Housing: High Temperature Thermoplastic, LCP, Color: Black, UL94V-0
1-2 终端和开关 Terminal and Switch: Phosphor Bronze, T=0.15mm
- 电镀 Plating:
接触电阻 Contact Area: Gold 3u"
焊接区域 Solder Area: Gold Flash.
底镀 Underplating: Ni overall 50u" min.
- 规格 Specification:
3-1 触点额定电流 Contact Current Rating: 0.5A
3-2 绝缘耐压 Dielectric Withstanding Voltage: AC500V r.m.s.
3-3 绝缘电阻 Insulation Resistance: 1000 mΩ Minimum, at DC 500V.
3-4 接触电阻 Contact Resistance: 100 mΩ Maximum.
3-5 寿命 Mating Cycle: 100,000 Insertions.

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE:
CHECKED		UNIT: mm/in	Smart card CONN
APPROVED		SIZE: A4	PART NO.: XKSMC-2100-135
			DWG NO.: X-XKSMC-2100-135
		SCALE	PAGE
		N/A	1/1
		REVISION	A1